

§ 63.11504

40 CFR Ch. I (7–1–13 Edition)

| Citation  | Subject   | Applies to Subpart VVVVVV? | Explanation  |
|---|---|----------------------------|--|
| 63.10(b)(2)(iii) .....                                      | Maintenance Records ....<br>Actions Taken to Minimize Emissions During SSM.                 | Yes.                       |  |
| 63.10(b)(2)(iv) and (v) .....                               |   | No.                        |  |
| 63.10(b)(2)(vi), (x), (xi), (xiii) .....                    |   | Yes .....                  | Apply only if you use CEMS to demonstrate compliance with alternative standard in § 63.11496(e). |
| 63.10(b)(2)(vii)–(b)(2)(ix), (b)(2)(xii), (b)(2)(xiv) ..... |   | Yes.                       |  |
| 63.10(b)(3) .....   |   | Yes.                       |  |
| 63.10(c)(1), (c)(5)–(c)(6), (c)(13)–(c)(14) .....           |   | Yes .....                  | Apply only if you use CEMS to demonstrate compliance with alternative standard in § 63.11496(e). |
| 63.10(c)(7)–(8) .....                                       | Additional Recordkeeping Requirements for CMS—Identifying Exceedances and Excess Emissions. | Yes.                       |  |
| 63.10(c)(10) .....  | Recordkeeping Nature and Cause of Malfunctions.   | No .....                   | See § 63.11501(c)(1)(vii) and (viii) for malfunctions recordkeeping requirements.                |
| 63.10(c)(11) .....  | Recording Corrective Actions.   | No .....                   | See § 63.11501(c)(1)(vii) and (viii) for malfunctions recordkeeping requirements.                |
| 63.10(c)(12) .....  |   | Yes.                       |  |
| 63.10(c)(15) .....  | Use of SSM Plan .....   | No.                        |  |
| 63.10(c)(2)–(c)(4), (c)(9) .....                            | Reserved .....  | No.                        |  |
| 63.10(d)(1), (d)(2), (d)(4), (e)(1), (e)(2), (f) .....      | Reporting Requirements  | Yes.                       |  |
| 63.10(d)(3) .....   |   | No .....                   | Subpart VVVVVV does not include opacity or VE limits.  |
| 63.10(d)(5) .....   | SSM Reports .....   | No .....                   | See § 63.11501(d)(8) for reporting requirements for malfunctions.                                |
| 63.10(e)(1)–(e)(2) .....                                    |   | Yes .....                  | Apply only if you use CEMS to demonstrate compliance with alternative standard in § 63.11496(e). |
| 63.10(e)(3) .....   |   | Yes.                       |  |
| 63.10(e)(4) .....   |   | No .....                   | Subpart VVVVVV does not include opacity or VE limits.  |
| 63.11 .....   | Control Device Requirements.  | Yes.                       |  |
| 63.12 .....   | State Authorities and Delegations.  | Yes.                       |  |
| 63.13 .....   | Addresses .....   | Yes.                       |  |
| 63.14 .....   | Incorporations by Reference.  | Yes.                       |  |
| 63.15 .....   | Availability of Information and Confidentiality.  | Yes.                       |  |
| 63.16 .....   | Performance Track Provisions.   | Yes.                       |  |

[74 FR 56041, Oct. 29, 2009, as amended at 77 FR 75762, Dec. 21, 2012]

**Subpart WWWW—National Emission Standards for Hazardous Air Pollutants: Area Source Standards for Plating and Polishing Operations**

SOURCE: 73 FR 37741, July 1, 2008, unless otherwise noted.

APPLICABILITY AND COMPLIANCE DATES  
**§ 63.11504 Am I subject to this subpart?**

(a) You are subject to this subpart if you own or operate a plating and polishing facility that is an area source of hazardous air pollutant (HAP) emissions and meets the criteria specified in paragraphs (a)(1) through (3) of this section.

(1) A plating and polishing facility is a plant site that is engaged in one or

## Environmental Protection Agency

## § 63.11505

more of the processes listed in paragraphs (a)(1)(i) through (vi) of this section.

(i) Electroplating other than chromium electroplating (i.e., non-chromium electroplating).

(ii) Electroless or non-electrolytic plating.

(iii) Other non-electrolytic metal coating processes, such as chromate conversion coating, nickel acetate sealing, sodium dichromate sealing, and manganese phosphate coating; and thermal spraying.

(iv) Dry mechanical polishing of finished metals and formed products after plating or thermal spraying.

(v) Electroforming.

(vi) Electropolishing.

(2) A plating or polishing facility is an area source of HAP emissions, where an area source is any stationary source or group of stationary sources within a contiguous area under common control that does not have the potential to emit any single HAP at a rate of 9.07 megagrams per year (Mg/yr) (10 tons per year (tpy)) or more and any combination of HAP at a rate of 22.68 Mg/yr (25 tpy) or more.

(3) Your plating and polishing facility uses or has emissions of compounds of one or more plating and polishing metal HAP, which means any compound of any of the following metals: cadmium, chromium, lead, manganese, and nickel, as defined in § 63.11511, "What definitions apply to this subpart?" With the exception of lead, plating and polishing metal HAP also include any of these metals in the elemental form.

(b) [Reserved]

[73 FR 37741, July 1, 2008, as amended at 76 FR 57919, Sept. 19, 2011]

### § 63.11505 What parts of my plant does this subpart cover?

(a) This subpart applies to each new or existing affected source, as specified in paragraphs (a)(1) through (3) of this section, at all times. A new source is defined in § 63.11511, "What definitions apply to this subpart?"

(1) Each tank that contains one or more of the plating and polishing metal HAP, as defined in § 63.11511, "What definitions apply to this subpart?", and is used for non-chromium

electroplating; electroforming; electropolishing; electroless plating or other non-electrolytic metal coating operations, such as chromate conversion coating, nickel acetate sealing, sodium dichromate sealing, and manganese phosphate coating.

(2) Each thermal spraying operation that applies one or more of the plating and polishing metal HAP, as defined in § 63.11511, "What definitions apply to this subpart?"

(3) Each dry mechanical polishing operation that emits one or more of the plating and polishing metal HAP, as defined in § 63.11511, "What definitions apply to this subpart?"

(b) An affected source is existing if you commenced construction or reconstruction of the affected source on or before March 14, 2008.

(c) An affected source is new if you commenced construction or reconstruction of the affected source after March 14, 2008.

(d) This subpart does not apply to any of the process units or operations described in paragraphs (d)(1) through (6) of this section.

(1) Process units that are subject to the requirements of 40 CFR part 63, subpart N (National Emission Standards for Chromium Emissions from Hard and Decorative Chromium Electroplating and Chromium Anodizing Tanks).

(2) Research and development process units, as defined in § 63.11511, "What definitions apply to this subpart?"

(3) Process units that are used strictly for educational purposes.

(4) Plating, polishing, coating, or thermal spraying conducted to repair surfaces or equipment.

(5) Dry mechanical polishing conducted to restore the original finish to a surface.

(6) Any plating or polishing process that uses process materials that contain cadmium, chromium, lead, or nickel (as the metal) in amounts less than 0.1 percent by weight, or that contain manganese in amounts less than 1.0 percent by weight (as the metal), as used. Information used to determine the amount of plating and polishing metal HAP in materials used in the